

## Product Change Notice (PCN)

**Date:** 03/22/2023

**PCN Number:** PCN-0450022R-01

To Our Customers:

We appreciate your use of our products. Our commitment in maintaining and improving processes is demonstrated by plans to enhance our product quality, reliability, and manufacturability. The purpose of this notice is to inform you of a product change.

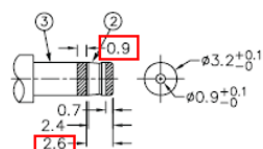
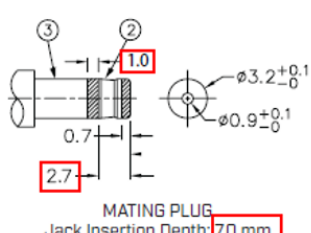
Product(s) Affected: *PJ-074-SMT-TR*

Reason(s) for Change: *Manufacturing Improvement processes*

Description of Change: *Product re-engineered for improved manufacturability and production yield. See image below as reference for product changes. Cosmetic differences may be visible and do not affect the form, fit or function of the product.*

PREVIOUS CUI DEVICES DETAIL / IMAGE			NEW CUI DEVICES DETAIL / IMAGE			
	MATERIAL	PLATING		DESCRIPTION	MATERIAL	PLATING/COLOR
terminal 1	brass	gold flash	terminal 1	brass		gold flash
terminal 2	copper alloy	gold flash	terminal 2	copper alloy		gold flash
terminal 3	copper alloy	gold flash	terminal 3	copper alloy		gold flash
plastic	PA6T or equivalent		housing	PA10T (UL94V-0)		black

 <p>MATING PLUG Jack Insertion Depth: 7.2mm</p>	 <p>MATING PLUG Jack Insertion Depth: 7.0mm</p>
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PREVIOUS CUI DEVICE'S DETAIL / IMAGE	NEW CUI DEVICE'S DETAIL / IMAGE																																										
<p><b>SOLDERABILITY</b></p> <table border="1"> <thead> <tr> <th>parameter</th> <th>conditions/description</th> <th>min</th> <th>typ</th> <th>max</th> <th>units</th> </tr> </thead> <tbody> <tr> <td>reflow storage</td> <td>at relative humidity &lt;math&gt;&lt; 80\%&lt;/math&gt;</td> <td></td> <td></td> <td>40</td> <td><math>^{\circ}\text{C}</math></td> </tr> <tr> <td>reflow soldering</td> <td>see reflow profile</td> <td>255</td> <td>260</td> <td>265</td> <td><math>^{\circ}\text{C}</math></td> </tr> </tbody> </table> <p>drying conditions<sup>1</sup> parts in reel: bake at 42<math>^{\circ}\text{C}</math> 15<math>^{\circ}\text{C}</math> for 72 hours parts removed from reel: bake at 42<math>^{\circ}\text{C}</math> 15<math>^{\circ}\text{C}</math> for 10 hours</p> <p>Note: 1. Must reflow solder within 72 hours from opening vacuum packaging at a temperature &lt;math&gt;125^{\circ}\text{C}&lt;/math&gt; &lt;math&gt;5&lt;/math&gt; relative humidity &lt;math&gt;60\%&lt;/math&gt;. 2. When ascending floor life by 172 hours</p>	parameter	conditions/description	min	typ	max	units	reflow storage	at relative humidity <math>< 80\%</math>			40	$^{\circ}\text{C}$	reflow soldering	see reflow profile	255	260	265	$^{\circ}\text{C}$	<p><b>SOLDERABILITY</b></p> <table border="1"> <thead> <tr> <th>parameter</th> <th>conditions/description</th> <th>min</th> <th>typ</th> <th>max</th> <th>units</th> </tr> </thead> <tbody> <tr> <td>wave soldering</td> <td>dipped in solder pot for 5-10.5 seconds</td> <td>255</td> <td>260</td> <td>265</td> <td><math>^{\circ}\text{C}</math></td> </tr> <tr> <td>reflow storage</td> <td>&lt;math&gt;-5&lt;/math&gt; to &lt;math&gt;25^{\circ}\text{C}&lt;/math&gt;, 20-80% humidity refl unpopulated: use within 1 month refl unpopulated: use within 6 months</td> <td></td> <td></td> <td></td> <td></td> </tr> <tr> <td>reflow soldering</td> <td>see reflow profile</td> <td>260</td> <td>265</td> <td>270</td> <td><math>^{\circ}\text{C}</math></td> </tr> </tbody> </table> <p>Note: 1. CUI Devices recommends usage of this product within 2 hours after FRB is opened. After 6 hours, CUI Devices recommends drying the parts prior to use.</p>	parameter	conditions/description	min	typ	max	units	wave soldering	dipped in solder pot for 5-10.5 seconds	255	260	265	$^{\circ}\text{C}$	reflow storage	<math>-5</math> to <math>25^{\circ}\text{C}</math>, 20-80% humidity refl unpopulated: use within 1 month refl unpopulated: use within 6 months					reflow soldering	see reflow profile	260	265	270	$^{\circ}\text{C}$
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<p><b>PACKAGING</b></p> <p>units: mm</p> <p>Reel Size: 0301 mm Reel QTY: 300 pcs per reel</p> <p>SOLDER MATERIAL DIRECTION INPUT MATERIAL DIRECTION COVER TAPE CARRIER TAPE A: Empty 160 mm min. B: Empty 150 mm min. C: Cover 400 mm min.</p> <p>PLASTIC REEL COVER TAPE CARRIER TAPE REEL</p>	<p><b>PACKAGING</b></p> <p>units: mm</p> <p>Reel Size: 0300 mm Reel QTY: 300 pcs per reel</p> <p>4.00±0.10 2.00±0.10 16.00±0.10 1.25±0.05 2.00±0.10 0.4</p> <p>OUTER PULL OFF DIRECTION INNER PULL OFF DIRECTION REEL CARRIER TAPE PLASTIC REEL</p> <p>REEL SPEED 300MM/MIN 1.140±0.07 1.14±0.06</p>																																										

Affected Date Code: **03/11/2023**

Product Availability: *Pertaining to market availability*

PCN Approval:

Operations/Quality

Product Management